Din-Tek SEMICONDUCTOR

DTQ33250

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N-Channel 25 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)[a, e]	Q_g (Typ.)
25	0.0013 at V_{GS} = 10 V	80	70 nC
	0.0018 at V_{GS} = 4.5 V	65	

FEATURES

- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested

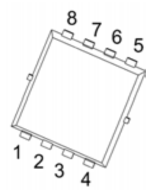
RoHS COMPLIANT

APPLICATIONS

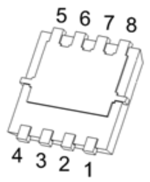
- Notebook PC Core
- VRM/POL

PDFN 3.3x3.3

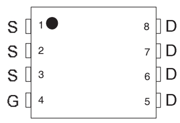
Top View

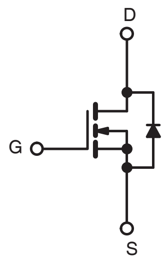


Bottom View



Top View





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	25	V
Gate-Source Voltage		V_{GS}	± 12	
Continuous Drain Current (T_J = 175 °C)	T_C = 25 °C	I_D	80[a, e]	A
	T_C = 70 °C		65[e]	
	T_A = 25 °C		41[b, c]	
	T_A = 70 °C		33[b, c]	
Pulsed Drain Current		I_{DM}	320	
Avalanche Current Pulse	L = 0.1 mH	I_{AS}	72	
Single Pulse Avalanche Energy		E_{AS}	105	mJ
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	80[a, e]	A
	T_A = 25 °C		7.5[b, c]	
Maximum Power Dissipation	T_C = 25 °C	P_D	55	W
	T_C = 70 °C		40	
	T_A = 25 °C		5.8[b, c]	
	T_A = 70 °C		4.1[b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient[b, d]	t ≤ 10 s	R_{thJA}	22	35	°C/W
Maximum Junction-to-Case	Steady State	R_{thJC}	2.4	4	

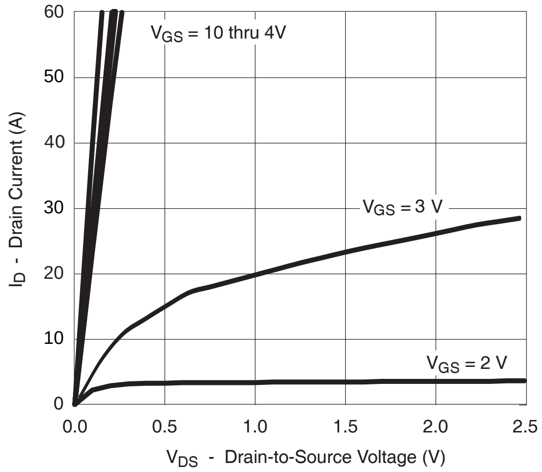
Notes:
a. Based on T_C = 25 °C.
b. Surface mounted on 1" x 1" FR4 board.
c. t = 10 s.
d. Maximum under steady state conditions is 90 °C/W.
e. Calculated based on maximum junction temperature. Package limitation current is 80 A.

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
Parameter	**Symbol**	**Test Conditions**	**Min .**	**Typ.**	**Max.**	**Unit**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 μA	25			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = 250 μA		35		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 5.5		
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 μA	0.5		2.5	V
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 20 V, V_{GS} = 0 V			1	μA
		V_{DS} = 20 V, V_{GS} = 0 V, T_J = 55 °C			10	
On-State Drain Current[a]	$I_{D(on)}$	$V_{DS} \geq$ 5 V, V_{GS} = 10 V	80			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 15 A		0.0013	0.0021	Ω
		V_{GS} = 4.5 V, I_D = 10 A		0.0018	0.0028	
Forward Transconductance[a]	g_{fs}	V_{DS} = 20 V, I_D = 15 A		140		S
Dynamic[b]						
Input Capacitance	C_{iss}	V_{DS} = 20 V, V_{GS} = 0 V, f = 1 MHz		3800		pF
Output Capacitance	C_{oss}			880		
Reverse Transfer Capacitance	C_{rss}			90		
Total Gate Charge	Q_g	V_{DS} = 20 V, V_{GS} = 10 V, I_D = 15 A		70		nC
		V_{DS} = 20 V, V_{GS} = 4.5 V, I_D = 10 A		30		
Gate-Source Charge	Q_{gs}			16		
Gate-Drain Charge	Q_{gd}			3.8		
Gate Resistance	R_g	f = 1 MHz		1.0	2.1	Ω
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 20 V, R_L = 0.555 Ω $I_D \cong$ 15 A, V_{GEN} = 10 V, R_g = 1 Ω		12		ns
Rise Time	t_r			6		
Turn-Off Delay Time	$t_{d(off)}$			38		
Fall Time	t_f			4.5		
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 20 V, R_L = 0.625 Ω $I_D \cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		25		
Rise Time	t_r			10		
Turn-Off Delay Time	$t_{d(off)}$			45		
Fall Time	t_f			7.2		
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C			80	A
Pulse Diode Forward Current[a]	I_{SM}				320	
Body Diode Voltage	V_{SD}	I_S = 12 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = 10 A, di/dt = 100 A/μs, T_J = 25 °C		20		ns
Body Diode Reverse Recovery Charge	Q_{rr}			20		nC
Reverse Recovery Fall Time	t_a			59		ns
Reverse Recovery Rise Time	t_b			15		

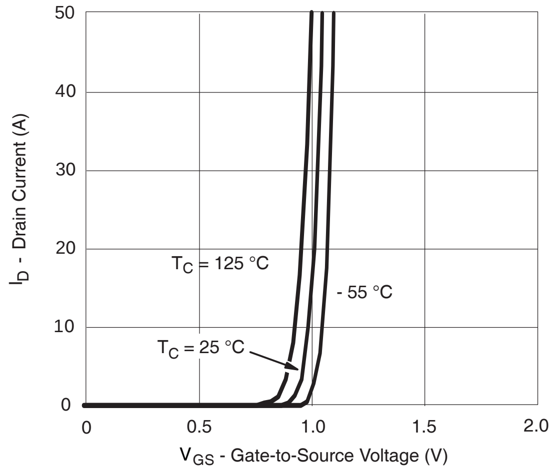
Notes:
a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

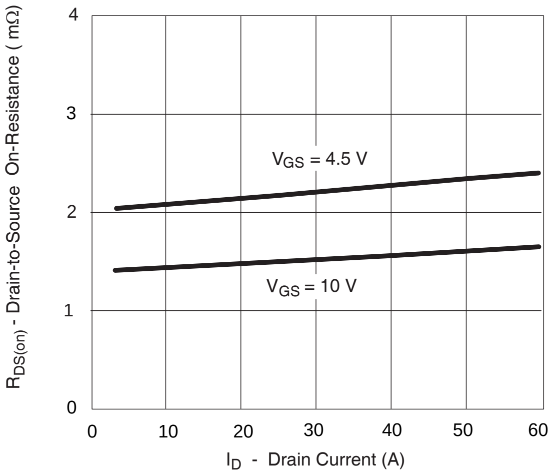
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



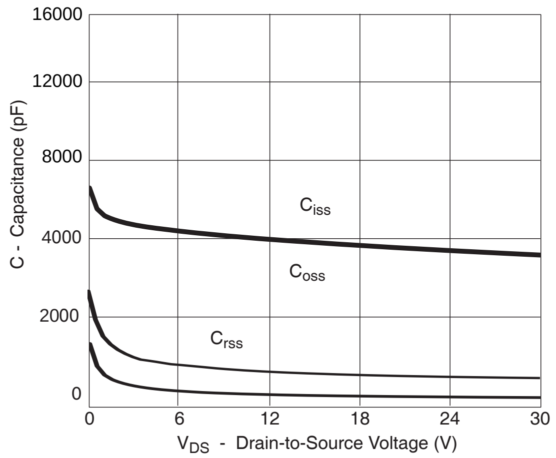
Output Characteristics



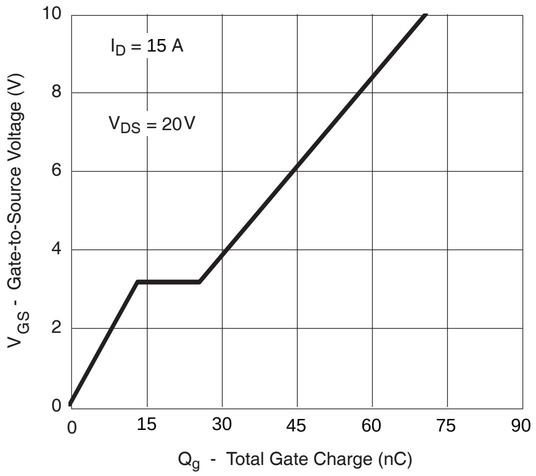
Transfer Characteristics



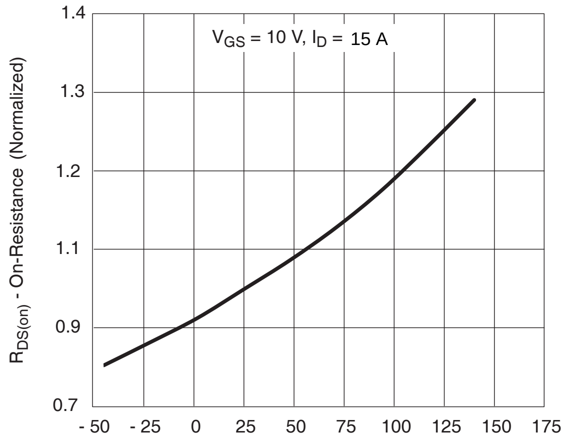
$R_{DS(on)}$ vs. Drain Current



Capacitance

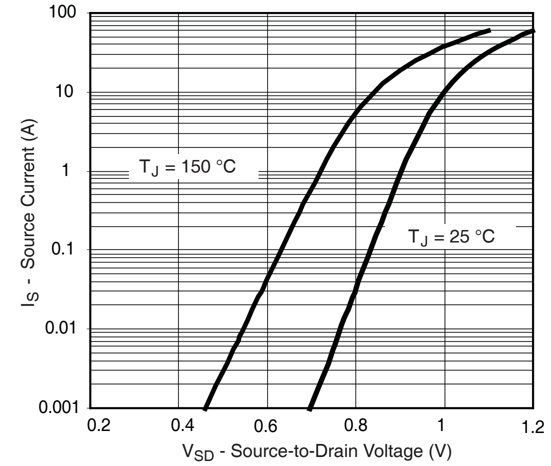


Gate Charge

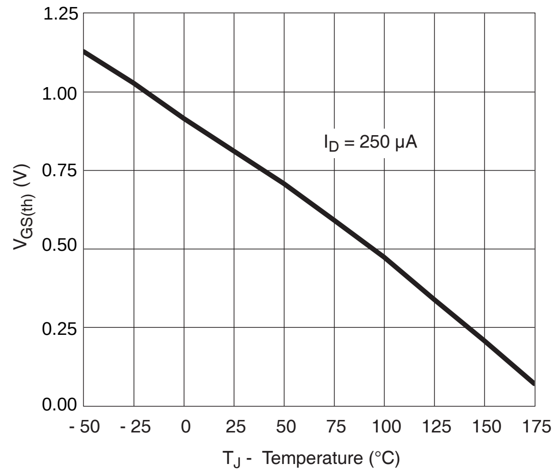


On-Resistance vs. Junction Temperature

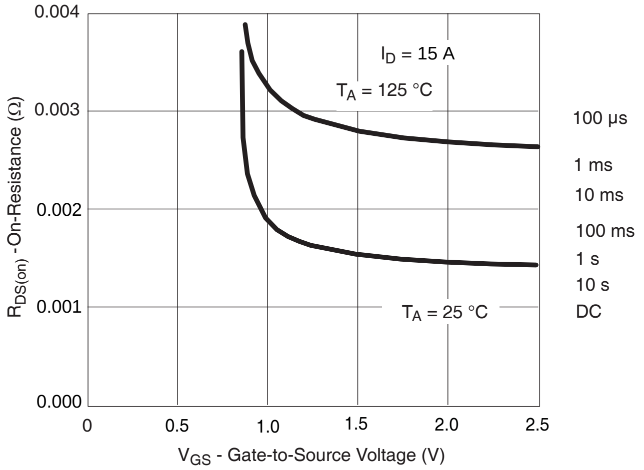
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



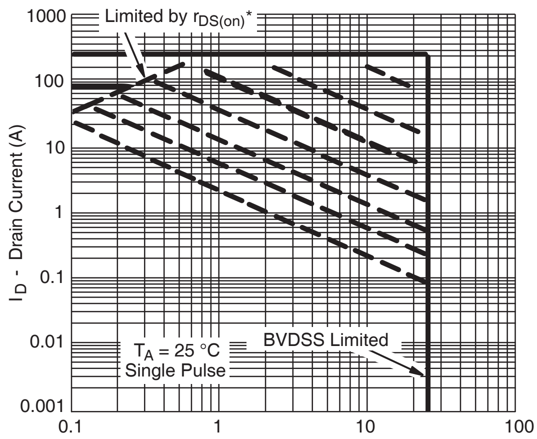
Forward Diode Voltage vs. Temperature



Threshold Voltage



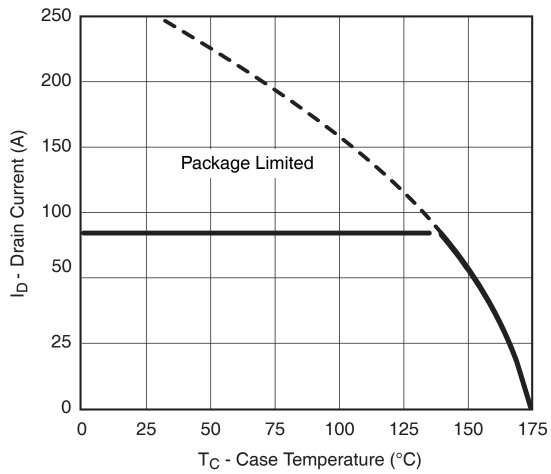
$R_{DS(on)}$ vs. V_{GS} vs. Temperature



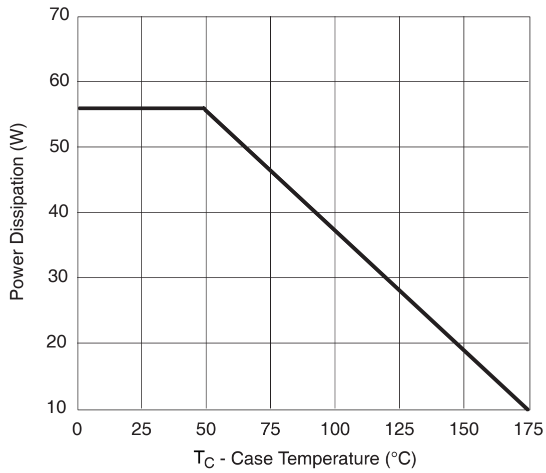
*V_{GS} > minimum V_{GS} at which $r_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

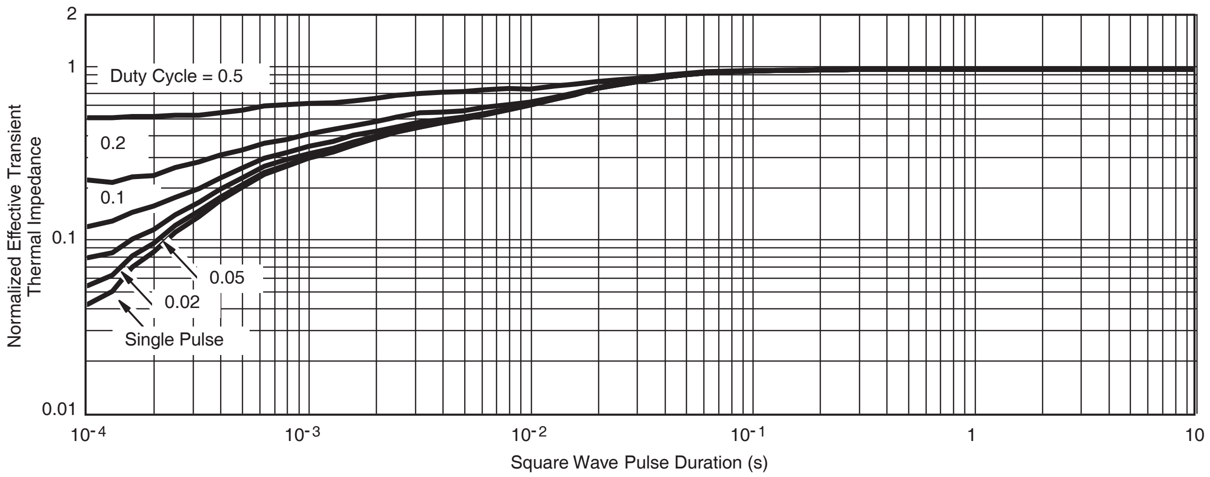


Current Derating*



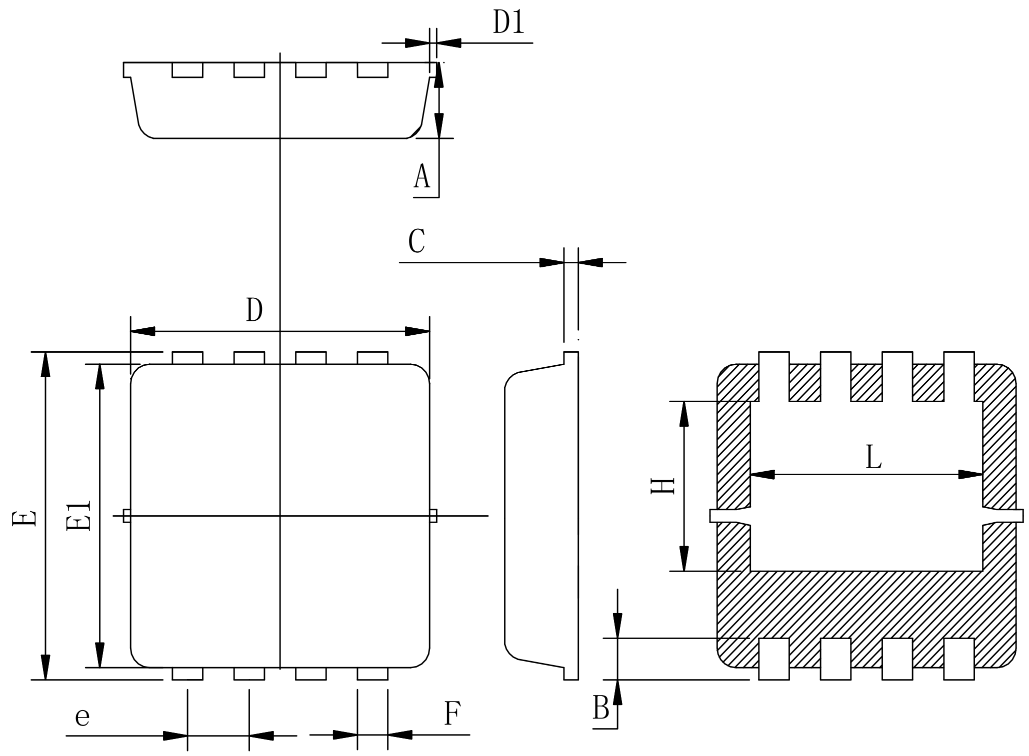
Power Derating

* The power dissipation P_D is based on $T_{J(max)}$ = 175 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case

PDFN 3.3X3.3 PACKAGE OUTLINE



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Typ	Max
A	0.600	0.775	1.000
B	0.20	0.38	0.55
C	0.05	0.15	0.40
D	3.10	3.25	3.50
D1	-	-	0.15
E	3.15	3.35	3.50
E1	2.60	3.10	3.45
e	0.50	0.65	0.80
F	0.15	0.32	0.45
H	1.25	1.73	2.10
L	2.20	2.45	2.85

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